

PCN Number:	20201217000.1		PCN Date:	Dec 18 2020	
Title:	Qualification of TI Malaysia as an alternate AT site for Select Devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Mar 18 2021	Estimated Sample Availability:	Date provided at sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of TI Malaysia as an additional AT for the list of devices shown below. There are no construction differences between the current site and TI Malaysia.					
Reason for Change:					
Supply continuity					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp		
Changes to product identification resulting from this PCN:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
TI Mexico	MEX	MEX	Aguascalientes		
TI Malaysia	MLA	MYS	Kuala Lumpur		
Sample product shipping label (not actual product label)					
<p> TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)TO:1750 </p> <p> G4 </p> <p> (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS </p>					
Product Affected:					
LM2903BIDR	LM393BIDR				

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM393BIDR	QBS Product Reference: LM2903BQDRQ1	QBS Package Reference: TMP1075D
PC	Preconditioning	level 1@ 260C	1/308/0	-	3/924/0
HTOL	High Temp Operating Life , 150C	300 Hours	-	3/231/0	-
HAST	**Biased HAST, 130C/85%RH	96 Hours	1/77/0	-	3/231/0
UHAST	**Unbiased HAST, 130C/85%RH	96 Hours	1/77/0	-	3/231/0
TC	**Temperature Cycles, -65C/150C	500 Cycles	1/77/0	-	3/231/0
HTSL	**High Temp. Storage Bake , 150C	1000 Hours	1/77/0	-	-
HTSL	**High Temp. Storage Bake , 170C	420 Hours	-	-	3/231/0
HBM	ESD HBM	2000V	-	3/9/0	-
CDM	ESD CDM	1500V	1/3/0	3/9/0	-
LU	Latch-up	JESD78	-	3/18/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	-	-
MQ	Manufacturability (Test)	(per mfg. Site specification)	Pass	-	-
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	-	-

- QBS: Qual By Similarity

- Qual Device LM393BIDR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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